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July 2007

FDS9958

Dual P-Channel PowerTrench[®] MOSFET -60V, -2.9A, $105m\Omega$

Features

- Max $r_{DS(on)} = 105 \text{m}\Omega$ at $V_{GS} = -10 \text{V}$, $I_D = -2.9 \text{A}$
- Max $r_{DS(on)} = 135 \text{m}\Omega$ at $V_{GS} = -4.5 \text{V}$, $I_D = -2.5 \text{A}$
- RoHS Compliant



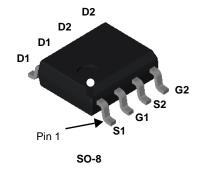
General Description

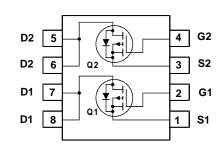
These P-channel logic level specified MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

These devices are well suited for portable electronics applications: load switching and power management, battery charging and protection circuits.

Applications

- Load Switch
- Power Management





MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V _{DS}	Drain to Source Voltage		-60	V	
V _{GS}	Gate to Source Voltage		±20	V	
1	Drain Current -Continuous	(Note 1a)	-2.9	^	
^I D	-Pulsed		-12	— A	
E _{AS}	Single Pulse Avalanche Energy	(Note 3)	54	mJ	
	Power Dissipation for Dual Operation		2		
P_{D}	Power Dissipation	(Note 1a)	1.6	W	
	Power Dissipation	(Note 1b)	0.9		
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	40	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	78	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS9958	FDS9958	SO-8	330mm	12mm	2500units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-60			V
ΔBV_{DSS} ΔT_{J}	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, referenced to 25°C		-52		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -48V,$ $V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			-1 -100	μА
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1.0	-1.6	-3.0	V
$\Delta V_{GS(th)}$ ΔT_J	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = -250\mu\text{A}$, referenced to 25°C		4		mV/°C
		$V_{GS} = -10V, I_D = -2.9A$		82	105	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = -4.5V, I_D = -2.5A$		103	135	mΩ
, ,		$V_{GS} = -10V$, $I_D = -2.9A$, $T_J = 125$ °C		131	190	Ī
9 _{FS}	Forward Transconductance	$V_{DD} = -5V, I_D = -2.9A$		7.7		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 20V V 0V	765	1020	pF
C _{oss}	Output Capacitance	$V_{DS} = -30V, V_{GS} = 0V,$ f = 1MHz	90	120	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1111112	40	65	pF

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			6	12	ns
t _r	Rise Time	$V_{DD} = -30V, I_{D} = -2.9A,$ $V_{GS} = -10V, R_{GEN} = 6\Omega$		3	10	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = -10V, K _{GEN} = 652		27	43	ns
t _f	Fall Time			6	12	ns
Q_g	Total Gate Charge	$V_{GS} = 0V \text{ to } -10V$		16	23	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } -4.5V$ $V_{DD} = -30V,$ $I_{D} = -2.9A$		8	12	nC
Q _{gs}	Gate to Source Charge	I _D = -2.9A		2		nC
Q_{gd}	Gate to Drain "Miller" Charge			3		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0V, I_{S} = -1.3A$ (Note 2)		-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	L = 2.04 di/dt = 1004/vo		26	42	ns
Q _{rr}	Reverse Recovery Charge	$I_F = -2.9A$, di/dt = 100A/ μ s		21	35	nC

NOTES

^{1.} R_{0,1A} is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,1C} is guaranteed by design while R_{0,CA} is determined by the user's board design.



a) 78°C/W when mounted on a 1 in² pad of 2 oz copper



b) 135°C/W when mounted on a minimun pad

- 2. Pulse Test: Pulse Width < $300\mu\text{s},$ Duty cycle < 2.0%.
- 3. UIL condition: Starting T_J = 25°C, L = 3mH, I_{AS} = 6A, V_{DD} = 60V, V_{GS} = 10V.

Typical Characteristics $T_J = 25$ °C unless otherwise noted

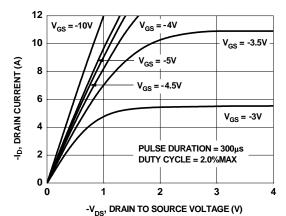


Figure 1. On-Region Characteristics

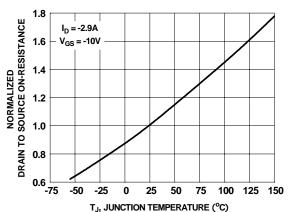


Figure 3. Normalized On-Resistance vs Junction Temperature

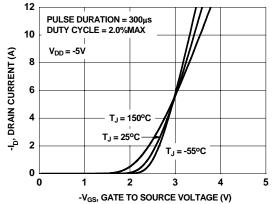


Figure 5. Transfer Characteristics

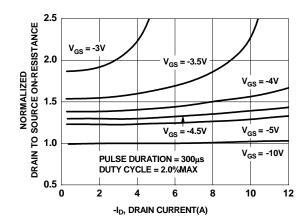


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

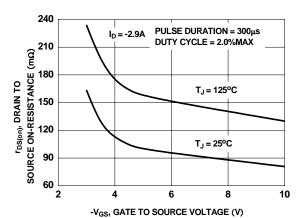


Figure 4. On-Resistance vs Gate to Source Voltage

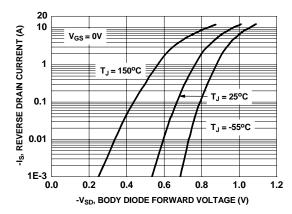


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

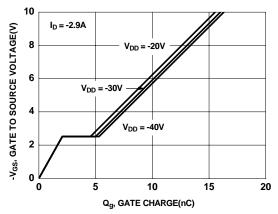


Figure 7. Gate Charge Characteristics

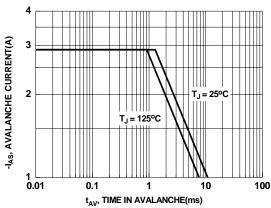


Figure 9. Unclamped Inductive Switching Capability

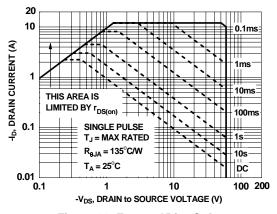


Figure 11. Forward Bias Safe Operating Area

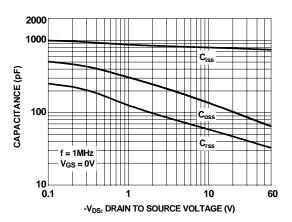


Figure 8. Capacitance vs Drain to Source Voltage

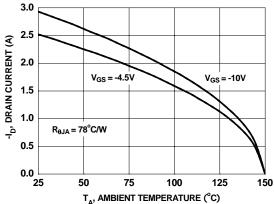


Figure 10. Maximum Continuous Drain Current vs Ambient Temperature

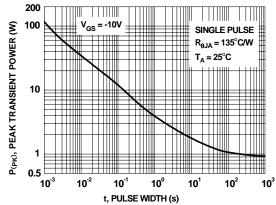


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

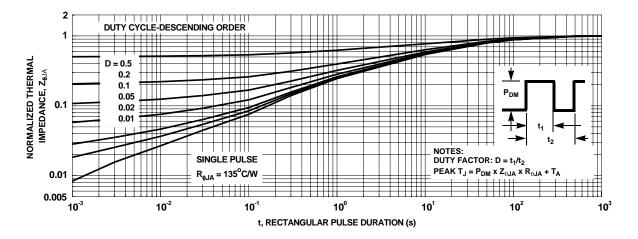


Figure 13. Transient Thermal Response Curve





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